

Application Number: 10/654,167
Reply to O.A. of April 13, 2005

Dkt. No.: DT-024-US-01

AMENDMENTS TO THE CLAIMS

Please amend the claims as follows:

1. (Currently Amended) A hot melt adhesive composition comprising:
 - (a) an ethylene methyl methacrylate copolymer;
 - (b) a wax; and
 - (b)(c) a tackifying resin,
with the proviso that the composition does not include a surfactant or a copolymer of ethylene and n-butyl acrylate.
4. (Currently Amended) The composition of claim 3 2 further comprising an antioxidant.
8. (Currently Amended) The composition of claim 7 1 further comprising a block copolymer.
11. (Currently Amended) A hot melt adhesive composition consisting essentially of:
 - (a) an ethylene methyl methacrylate copolymer;
 - (b) a wax; and
 - (b)(c) a tackifying resin,
14. (Currently Amended) The composition of claim 43 12 further consisting essentially of an antioxidant.
17. (Currently Amended) The composition of claim 46 11 further consisting essentially of a block copolymer.

Please cancel claims 3, 7, 13, and 16.

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DETAILED CLAIM LISTING

The listing of claims will replace all prior versions, and listings, of claims in the application.

1. (Currently Amended) A hot melt adhesive composition comprising:
 - (a) an ethylene methyl methacrylate copolymer;
 - (b) a wax; and
 - (b)(c) a tackifying resin,with the proviso that the composition does not include a surfactant or a copolymer of ethylene and n-butyl acrylate.
2. (Original) The composition of claim 1 further comprising an oil.
3. (Cancelled)
4. (Currently Amended) The composition of claim 3 2 further comprising an antioxidant.
5. (Original) The composition of claim 4 further comprising a copolymer.
6. (Original) The composition of claim 5 further comprising a block copolymer.
7. (Cancelled)
8. (Currently Amended) The composition of claim 7 1 further comprising a block copolymer.
9. (Original) A package formulation comprising:
 - (a) the composition of claim 1; and
 - (b) instructions for application of the composition to a substrate.

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10. (Withdrawn) A method of making the composition of claim 1.
11. (Currently Amended) A hot melt adhesive composition consisting essentially of:
 - (a) an ethylene methyl methacrylate copolymer;
 - (b) a wax; and
 - (b)(c) a tackifying resin.
12. (Original) The composition of claim 11 further consisting essentially of an oil.
13. (Cancelled)
14. (Currently Amended) The composition of claim 13 12 further consisting essentially of an antioxidant.
15. (Original) The composition of claim 14 further consisting essentially of a block copolymer.
16. (Cancelled)
17. (Currently Amended) The composition of claim 16 11 further consisting essentially of a block copolymer.
18. (Withdrawn) A method of making the composition of claim 11.
19. (Withdrawn) A method of using a hot melt adhesive composition comprising:
 - (a) providing a hot melt adhesive composition comprising:
 - (i) an ethylene methyl methacrylate copolymer; and
 - (ii) a tackifying resin,

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with the proviso that the composition does not include a surfactant or a copolymer
of ethylene and n-butyl acrylate; and
(b) applying the composition to a substrate.

20. (Withdrawn) The method of claim 19 wherein the method is a method of using
the hot melt adhesive for book binding.